

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-9. (canceled)

10. **(currently amended)** An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface and having an optical element;
a plurality of bonding pads disposed on the upper surface;
a plurality of bonding wires electrically connecting the chip to the bonding pads;
a transparent adhesive layer;

a window made of a transparent material mounted directly on the optical element of the chip by said transparent adhesive layer which is disposed between said window and said optical element for allowing light to transmit through the window and interact with the optical element;
and

an encapsulant formed on the substrate for fixing the window and encapsulating the chip and the bonding wires.

11. (previously presented) The optical semiconductor package as claimed in claim 10, wherein the encapsulant is formed by means of an overmolding process.

12. (original) The optical semiconductor package as claimed in claim 10, wherein the window further comprises a ledge for securing the window in the encapsulant.

13. (original) The optical semiconductor package as claimed in claim 10, wherein the encapsulant is made of an opaque material.

14. (original) The optical semiconductor package as claimed in claim 10, wherein the window is a lens.

15-19. (canceled)

20. (currently amended) An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface and having an optical element;
a plurality of bonding pads disposed on the upper surface;
a plurality of bonding wires electrically connecting the chip to the bonding pads ;
a window made of a transparent material for allowing light to transmit through the window and interact with the optical element;

a support supporting the window for positioning the window corresponding to the optical element of the chip; and

an encapsulant formed on the substrate for hermetically fixing the support on the substrate, wherein at least a portion of the encapsulant is formed directly on the substrate.

21. (previously presented) The optical semiconductor package as claimed in claim 20, wherein the encapsulant is formed by means of an overmolding process.

22. (previously presented) The optical semiconductor package as claimed in claim 20, wherein the window is hermetically disposed on the support.

23. (canceled)

24. (original) The optical semiconductor package as claimed in claim 20, wherein the window is a lens.

25. (canceled)

26. (previously presented) The optical semiconductor package as claimed in claim 10, wherein said optical element comprises one selected from the group consisting of an optical sensor and an imaging sensor.

27. (currently amended) An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface of said substrate and having an optical element on an upper surface of said chip;
a plurality of bonding pads disposed on the upper surface of said substrate;
a plurality of bonding wires electrically connecting the chip to the bonding pads;
a transparent adhesive layer;
a window made of a transparent material mounted on the optical sensor of the chip by said transparent adhesive layer which is disposed between said window and said optical sensor for allowing light to transmit through the window and interact with the optical sensor; and
an encapsulant formed on the substrate for fixing the window and encapsulating the chip and the bonding wires;

~~The optical semiconductor package as claimed in claim 26, wherein~~
said window has opposite upper and lower surfaces and a side surface connecting the upper and lower surfaces of said window;
said package ~~further comprises~~ a transparent adhesive layer directly, physically contacts

~~both attaching~~ the lower surface of said window ~~and~~ ~~[[to]]~~ an upper surface of said optical ~~sensor element~~ of said chip ~~and attaches the lower surface of said window and the upper surface of said optical sensor together;~~ and

said encapsulant surrounds said window and directly, physically contacts the side surface of said ~~windows~~ window, while leaving the upper surface of said ~~windows~~ window exposed from an upper surface of said encapsulant.

28. (previously presented) The optical semiconductor package as claimed in claim 20, wherein said optical element is an optically sensitive element.

29. (previously presented) An optical semiconductor package, comprising:
a substrate having opposite upper and lower surfaces;
a chip disposed on the upper surface of said substrate and having an optical sensor;
a plurality of bonding wires electrically connecting the chip to the substrate;
a supporting wall extending upwardly from the upper surface of said substrate;
a window made of a transparent material and supported by said supporting wall at a location above said optical sensor for allowing light to transmit through the window and interact with the optical sensor; and
an encapsulant formed on the upper surface of said substrate to surround said supporting wall.

30. (previously presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant includes

an outer portion covering an outer side surface of said supporting wall; and
an inner portion encapsulating said chip and said wires and covering an inner side surface of said supporting wall, wherein said inner portion of said encapsulant is transparent.

31. (previously presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant, said supporting wall, said window and said substrate together define a hermetically sealed cavity in which said chip, said optical sensor and said wires are disposed.

32. (new) The optical semiconductor package as claimed in claim 27, wherein the encapsulant is made of an opaque material.

33. (new) The optical semiconductor package as claimed in claim 32, wherein the window is a lens.

34. (new) The optical semiconductor package as claimed in claim 27, comprising a straight light path that extends from the upper surface of said window to the upper surface of said optical sensor and through said window and said adhesive layer only, wherein said light path does not extend through said encapsulant.

35. (new) The optical semiconductor package as claimed in claim 29, wherein said supporting wall comprises

- a first section extending upwardly from the upper surface of said substrate and inwardly toward the window, said first section having opposite upper and lower ends, the lower end being on the upper surface of said substrate;

- a second section extending inwardly from the upper end of the first section, said second section supporting thereon said window; and

- a third section extending upwardly from the lower end of said first section and outwardly away from the window, said third section being embedded in said encapsulant;

wherein said first and third sections define together a cavity receiving therein a portion of said encapsulant.